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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	80
Number of Logic Elements/Cells	640
Total RAM Bits	-
Number of I/O	159
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo640e-4f256i

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



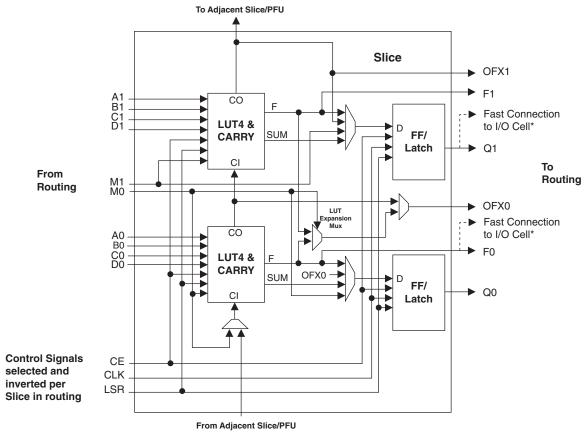
The devices use look-up tables (LUTs) and embedded block memories traditionally associated with FPGAs for flexible and efficient logic implementation. Through non-volatile technology, the devices provide the single-chip, high-security, instant-on capabilities traditionally associated with CPLDs. Finally, advanced process technology and careful design will provide the high pin-to-pin performance also associated with CPLDs.

The ispLEVER® design tools from Lattice allow complex designs to be efficiently implemented using the MachXO family of devices. Popular logic synthesis tools provide synthesis library support for MachXO. The ispLEVER tools use the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the MachXO device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.



There are 14 input signals: 13 signals from routing and one from the carry-chain (from the adjacent Slice/PFU). There are 7 outputs: 6 to the routing and one to the carry-chain (to the adjacent Slice/PFU). Table 2-1 lists the signals associated with each Slice.

Figure 2-5. Slice Diagram



Notes:

Some inter-Slice signals are not shown.

Table 2-1. Slice Signal Descriptions

Function	Туре	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0/M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FCIN	Fast Carry In ¹
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register Outputs
Output	Data signals	OFX0	Output of a LUT5 MUX
Output	Data signals	OFX1	Output of a LUT6, LUT7, LUT82 MUX depending on the Slice
Output	Inter-PFU signal	FCO	Fast Carry Out ¹

- 1. See Figure 2-4 for connection details.
- 2. Requires two PFUs.

^{*} Only PFUs at the edges have fast connections to the I/O cell.



Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM, and ROM. The Slice in the PFF is capable of all modes except RAM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SP 16x2	ROM 16x1 x 2
PFF Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	N/A	ROM 16x1 x 2

Logic Mode: In this mode, the LUTs in each Slice are configured as 4-input combinatorial lookup tables (LUT4). A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7, and LUT8 can be constructed by concatenating other Slices.

Ripple Mode: Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/Subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Ripple mode multiplier building block
- · Comparator functions of A and B inputs
 - A greater-than-or-equal-to B
 - A not-equal-to B
 - A less-than-or-equal-to B

Two additional signals, Carry Generate and Carry Propagate, are generated per Slice in this mode, allowing fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode: In this mode, distributed RAM can be constructed using each LUT block as a 16x2-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

The ispLEVER design tool supports the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Figure 2-6 shows the distributed memory primitive block diagrams. Dual port memories involve the pairing of two Slices. One Slice functions as the read-write port, while the other companion Slice supports the read-only port. For more information on RAM mode in MachXO devices, please see details of additional technical documentation at the end of this data sheet.

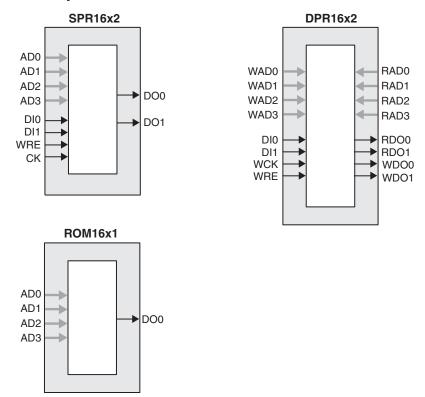
Table 2-3. Number of Slices Required For Implementing Distributed RAM

	SPR16x2	DPR16x2
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM



Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x 2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

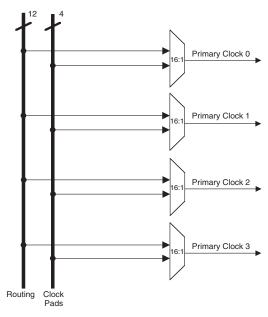


The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

Clock/Control Distribution Network

The MachXO family of devices provides global signals that are available to all PFUs. These signals consist of four primary clocks and four secondary clocks. Primary clock signals are generated from four 16:1 muxes as shown in Figure 2-7 and Figure 2-8. The available clock sources for the MachXO256 and MachXO640 devices are four dual function clock pins and 12 internal routing signals. The available clock sources for the MachXO1200 and MachXO2280 devices are four dual function clock pins, up to nine internal routing signals and up to six PLL outputs.

Figure 2-7. Primary Clocks for MachXO256 and MachXO640 Devices





The EBR memory supports three forms of write behavior for single or dual port operation:

- 1. **Normal** data on the output appears only during the read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.
- 2. **Write Through** a copy of the input data appears at the output of the same port. This mode is supported for all data widths.
- 3. **Read-Before-Write** when new data is being written, the old contents of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

FIFO Configuration

The FIFO has a write port with Data-in, CEW, WE and CLKW signals. There is a separate read port with Data-out, RCE, RE and CLKR signals. The FIFO internally generates Almost Full, Full, Almost Empty and Empty Flags. The Full and Almost Full flags are registered with CLKW. The Empty and Almost Empty flags are registered with CLKR. The range of programming values for these flags are in Table 2-7.

Table 2-7. Programmable FIFO Flag Ranges

Flag Name	Programming Range
Full (FF)	1 to (up to 2 ^N -1)
Almost Full (AF)	1 to Full-1
Almost Empty (AE)	1 to Full-1
Empty (EF)	0

N = Address bit width

The FIFO state machine supports two types of reset signals: RSTA and RSTB. The RSTA signal is a global reset that clears the contents of the FIFO by resetting the read/write pointer and puts the FIFO flags in their initial reset state. The RSTB signal is used to reset the read pointer. The purpose of this reset is to retransmit the data that is in the FIFO. In these applications it is important to keep careful track of when a packet is written into or read from the FIFO.

Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-13.



of the devices also support differential input buffers. PCI clamps are available on the top Bank I/O buffers. The PCI clamp is enabled after V_{CC} , V_{CCAUX} , and V_{CCIO} are at valid operating levels and the device has been configured.

The two pads in the pair are described as "true" and "comp", where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

2. Left and Right sysIO Buffer Pairs

The sysIO buffer pairs in the left and right Banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (supporting ratioed and absolute input levels). The devices also have a differential driver per output pair. The referenced input buffer can also be configured as a differential input buffer. In these Banks the two pads in the pair are described as "true" and "comp", where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all V_{CCIO} Banks are active with valid input logic levels to properly control the output logic states of all the I/O Banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-up to VCCIO. The I/O pins will maintain the blank configuration until VCC, VCCAUX and VCCIO have reached satisfactory levels at which time the I/Os will take on the user-configured settings.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, the I/O buffers should be powered up along with the FPGA core fabric. Therefore, V_{CCIO} supplies should be powered up before or together with the V_{CC} and V_{CCAUX} supplies

Supported Standards

The MachXO sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS and LVTTL. The buffer supports the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5, and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, bus-keeper latch or none) and open drain. BLVDS and LVPECL output emulation is supported on all devices. The MachXO1200 and MachXO2280 support on-chip LVDS output buffers on approximately 50% of the I/Os on the left and right Banks. Differential receivers for LVDS, BLVDS and LVPECL are supported on all Banks of MachXO1200 and MachXO2280 devices. PCI support is provided in the top Banks of the MachXO1200 and MachXO2280 devices. Table 2-8 summarizes the I/O characteristics of the devices in the MachXO family.

Tables 2-9 and 2-10 show the I/O standards (together with their supply and reference voltages) supported by the MachXO devices. For further information on utilizing the sysIO buffer to support a variety of standards please see the details of additional technical documentation at the end of this data sheet.



the system. These capabilities make the MachXO ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The MachXO "C" devices ($V_{CC} = 1.8/2.5/3.3V$) have a sleep mode that allows standby current to be reduced dramatically during periods of system inactivity. Entry and exit to Sleep mode is controlled by the SLEEPN pin.

During Sleep mode, the logic is non-operational, registers and EBR contents are not maintained, and I/Os are tristated. Do not enter Sleep mode during device programming or configuration operation. In Sleep mode, power supplies are in their normal operating range, eliminating the need for external switching of power supplies. Table 2-11 compares the characteristics of Normal, Off and Sleep modes.

Table 2-11. Characteristics of Normal, Off and Sleep Modes

Characteristic	Normal	Off	Sleep	
SLEEPN Pin	High	_	Low	
Static Icc	Typical <10mA	0	Typical <100uA	
I/O Leakage	<10μΑ	<1mA	<10μΑ	
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	0	Normal Range	
Logic Operation	User Defined	Non Operational	Non operational	
I/O Operation	User Defined	Tri-state	Tri-state	
JTAG and Programming circuitry	Operational	Non-operational	Non-operational	
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained	

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up, along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to VCC is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically, the device enters sleep mode several hundred nanoseconds after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet shows a detailed timing diagram.

Oscillator

Every MachXO device has an internal CMOS oscillator. The oscillator can be routed as an input clock to the clock tree or to general routing resources. The oscillator frequency can be divided by internal logic. There is a dedicated programming bit to enable/disable the oscillator. The oscillator frequency ranges from 18MHz to 26MHz.

Configuration and Testing

The following section describes the configuration and testing features of the MachXO family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All MachXO devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port shares its power supply with one of the VCCIO Banks (MachXO256: V_{CCIO1}; MachXO640: V_{CCIO2}; MachXO1200 and MachXO2280: V_{CCIO5}) and can operate with LVCMOS3.3, 2.5, 1.8, 1.5, and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.



Table 3-1. LVDS DC Conditions

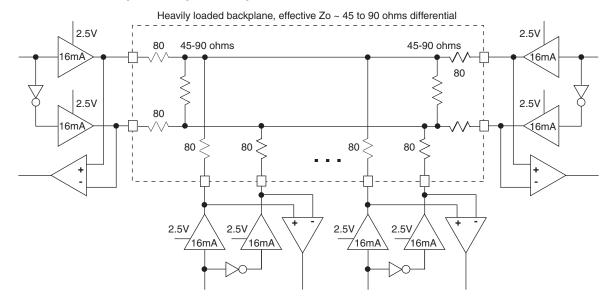
Over Recommended Operating Conditions

Parameter	Description	Typical	Units
Z _{OUT}	Output impedance	20	Ω
R _S	Driver series resistor	294	Ω
R _P	Driver parallel resistor	121	Ω
R _T	Receiver termination	100	Ω
V _{OH}	Output high voltage	1.43	V
V _{OL}	Output low voltage	1.07	V
V _{OD}	Output differential voltage	0.35	V
V _{CM}	Output common mode voltage	1.25	V
Z _{BACK}	Back impedance	100	Ω
I _{DC}	DC output current	3.66	mA

BLVDS

The MachXO family supports the BLVDS standard through emulation. The output is emulated using complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. The input standard is supported by the LVDS differential input buffer on certain devices. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

Figure 3-2. BLVDS Multi-point Output Example





For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

RSDS

The MachXO family supports the differential RSDS standard. The output standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The RSDS input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

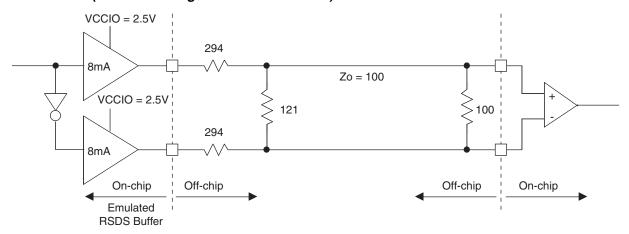


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z _{OUT}	Output impedance	20	Ohms
R _S	Driver series resistor	294	Ohms
R _P	Driver parallel resistor	121	Ohms
R _T	Receiver termination	100	Ohms
V _{OH}	Output high voltage	1.35	V
V _{OL}	Output low voltage	1.15	V
V _{OD}	Output differential voltage	0.20	V
V _{CM}	Output common mode voltage	1.25	V
Z _{BACK}	Back impedance	101.5	Ohms
I _{DC}	DC output current	3.66	mA



Typical Building Block Function Performance¹

Pin-to-Pin Performance (LVCMOS25 12mA Drive)

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	6.7	ns
4:1 MUX	4.5	ns
16:1 MUX	5.1	ns

Register-to-Register Performance

Function	-5 Timing	Units
Basic Functions		
16:1 MUX	487	MHz
16-bit adder	292	MHz
16-bit counter	388	MHz
64-bit counter	200	MHz
Embedded Memory Functions (1200 a	nd 2280 Devices Only)	
256x36 Single Port RAM	284	MHz
512x18 True-Dual Port RAM	284	MHz
Distributed Memory Functions		
16x2 Single Port RAM	434	MHz
64x2 Single Port RAM	320	MHz
128x4 Single Port RAM	261	MHz
32x2 Pseudo-Dual Port RAM	314	MHz
64x4 Pseudo-Dual Port RAM	271	MHz

The above timing numbers are generated using the ispLEVER design tool. Exact performance may vary with device and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.
Rev. A 0.19

Derating Logic Timing

Logic Timing provided in the following sections of the data sheet and the ispLEVER design tools are worst case numbers in the operating range. Actual delays may be much faster. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.



LCMXO256 and LCMXO640 Logic Signal Connections: 100 TQFP (Cont.)

	LCMXO256			LCMXO640				
Pin Number	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
85	PT4B	0	PCLK0_1**	С	PT6B	0	PCLK0_1**	
86	PT4A	0	PCLK0_0**	Т	PT5B	0	PCLK0_0**	С
87	PT3D	0		С	PT5A	0		Т
88	VCCAUX	-			VCCAUX	-		
89	PT3C	0		Т	PT4F	0		
90	VCC	-			VCC	-		
91	PT3B	0		С	PT3F	0		
92	VCCIO0	0			VCCIO0	0		
93	GNDIO0	0			GNDIO0	0		
94	PT3A	0		Т	PT3B	0		С
95	PT2F	0		С	PT3A	0		Т
96	PT2E	0		Т	PT2F	0		С
97	PT2D	0		С	PT2E	0		Т
98	PT2C	0		Т	PT2B	0		С
99	PT2B	0		С	PT2C	0		
100	PT2A	0		Т	PT2A	0		Т

^{*} NC for "E" devices.

^{**} Primary clock inputs are single-ended.



LCMXO256 and LCMXO640 Logic Signal Connections: 100 csBGA (Cont.)

		LCMXO256		9.0 0.9.	LCMXO640					
Ball Number	Ball Function	Bank	Dual Function	Differen- tial	Ball Number	Ball Function	Bank	Dual Function	Differen- tial	
P13	PB5A	1			P13	PB9C	2		Т	
M12*	SLEEPN	-	SLEEPN		M12*	SLEEPN	-	SLEEPN		
P14	PB5C	1		Т	P14	PB9D	2		С	
N13	PB5D	1		С	N13	PB9F	2			
N14	PR9B	0		С	N14	PR11D	1		С	
M14	PR9A	0		Т	M14	PR11B	1		С	
L13	PR8B	0		С	L13	PR11C	1		Т	
L14	PR8A	0		Т	L14	PR11A	1		Т	
M13	PR7D	0		С	M13	PR10D	1		С	
K14	PR7C	0		Т	K14	PR10C	1		Т	
K13	PR7B	0		С	K13	PR10B	1		С	
J14	PR7A	0		Т	J14	PR10A	1		Т	
J13	PR6B	0		С	J13	PR9D	1			
H13	PR6A	0		Т	H13	PR9B	1			
G14	GNDIO0	0			G14	GNDIO1	1			
G13	PR5D	0		С	G13	PR7B	1			
F14	PR5C	0		Т	F14	PR6C	1			
F13	PR5B	0		С	F13	PR6B	1			
E14	PR5A	0		Т	E14	PR5D	1			
E13	PR4B	0		С	E13	PR5B	1			
D14	PR4A	0		Т	D14	PR4D	1			
D13	PR3D	0		С	D13	PR4B	1			
C14	PR3C	0		Т	C14	PR3D	1			
C13	PR3B	0		С	C13	PR3B	1			
B14	PR3A	0		Т	B14	PR2D	1			
C12	PR2B	0		С	C12	PR2B	1			
B13	GNDIO0	0			B13	GNDIO1	1			
A13	PR2A	0		Т	A13	PT9F	0		С	
A12	PT5C	0			A12	PT9E	0		Т	
B11	PT5B	0		С	B11	PT9C	0			
A11	PT5A	0		Т	A11	PT9A	0			
B12	PT4F	0		С	B12	VCCIO0	0			
A10	PT4E	0		Т	A10	GNDIO0	0			
B10	PT4D	0		С	B10	PT7E	0			
A9	PT4C	0		Т	A9	PT7A	0			
A8	PT4B	0	PCLK0_1**	С	A8	PT6B	0	PCLK0_1**		
B8	PT4A	0	PCLK0_0**	Т	B8	PT5B	0	PCLK0_0**	С	
A7	PT3D	0		С	A7	PT5A	0		Т	
B7	VCCAUX	-			В7	VCCAUX	-			
A6	PT3C	0		Т	A6	PT4F	0			
B6	VCC	-			B6	VCC	-			
A5	PT3B	0		С	A5	PT3F	0			



LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP (Cont.)

	LCMXO640					LCMXO1200		LCMXO2280				
Pin Number	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
101	PR3D	1		С	PR4B	2		C*	PR5B	2		C*
102	PR3C	1		Т	PR4A	2		T*	PR5A	2		T*
103	PR3B	1		С	PR3D	2		С	PR4D	2		С
104	PR2D	1		С	PR3C	2		Т	PR4C	2		Т
105	PR3A	1		Т	PR3B	2		C*	PR4B	2		C*
106	PR2B	1		С	PR3A	2		T*	PR4A	2		T*
107	PR2C	1		Т	PR2B	2		С	PR3B	2		C*
108	PR2A	1		Т	PR2A	2		Т	PR3A	2		T*
109	PT9F	0		С	PT11D	1		С	PT16D	1		С
110	PT9D	0		С	PT11C	1		T	PT16C	1		Т
111	PT9E	0		Т	PT11B	1		С	PT16B	1		С
112	PT9B	0		С	PT11A	1		T	PT16A	1		Т
113	PT9C	0		Т	PT10F	1		С	PT15D	1		С
114	PT9A	0		Т	PT10E	1		Т	PT15C	1		Т
115	PT8C	0			PT10D	1		С	PT14B	1		С
116	PT8B	0		С	PT10C	1		Т	PT14A	1		Т
117	VCCIO0	0			VCCIO1	1			VCCIO1	1		
118	GNDIO0	0			GNDIO1	1			GNDIO1	1		
119	PT8A	0		Т	PT9F	1		С	PT12F	1		С
120	PT7E	0			PT9E	1		Т	PT12E	1		Т
121	PT7C	0			PT9B	1		С	PT12D	1		С
122	PT7A	0			PT9A	1		Т	PT12C	1		Т
123	GND	-			GND	-			GND	-		
124	PT6B	0	PCLK0_1***	С	PT7D	1	PCLK1_1***		PT10B	1	PCLK1_1***	
125	PT6A	0		Т	PT7B	1		С	PT9D	1		С
126	PT5C	0			PT7A	1		Т	PT9C	1		Т
127	PT5B	0	PCLK0_0***		PT6F	0	PCLK1_0***		РТ9В	1	PCLK1_0***	
128	VCCAUX	-			VCCAUX	-			VCCAUX	-		
129	VCC	-			VCC	-			VCC	-		
130	PT4D	0			PT5D	0		С	PT7B	0		С
131	PT4B	0		С	PT5C	0		Т	PT7A	0		Т
132	PT4A	0		Т	PT5B	0		С	PT6D	0		
133	PT3F	0			PT5A	0		Т	PT6E	0		Т
134	PT3D	0			PT4B	0			PT6F	0		С
135	VCCIO0	0			VCCIO0	0			VCCIO0	0		
136	GNDIO0	0			GNDIO0	0			GNDIO0	0		
137	PT3B	0		С	PT3D	0		С	PT4B	0		Т
138	PT2F	0		С	PT3C	0		Т	PT4A	0		С
139	PT3A	0		Т	PT3B	0		С	PT3B	0		С
140	PT2D	0		С	PT3A	0		Т	PT3A	0		Т
141	PT2E	0		Т	PT2D	0		С	PT2D	0		С
142	PT2B	0		С	PT2C	0		Т	PT2C	0		Т
143	PT2C	0		Т	PT2B	0		С	PT2B	0		С
144	PT2A	0		Т	PT2A	0		Т	PT2A	0		Т

^{*}Supports true LVDS outputs.

^{**}NC for "E" devices.

^{***}Primary clock inputs arer single-ended.



LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 256 caBGA / 256 ftBGA

		LCMX	O640			LCMXO1200				LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
GND	GNDIO3	3			GND	GNDI07	7			GND	GNDI07	7		
VCCIO3	VCCIO3	3			VCCIO7	VCCIO7	7			VCCI07	VCCIO7	7		
E4	NC				E4	PL2A	7		Т	E4	PL2A	7	LUM0_PLLT_FB_A	Т
E5	NC				E5	PL2B	7		С	E5	PL2B	7	LUM0_PLLC_FB_A	С
F5	NC				F5	PL3A	7		T*	F5	PL3A	7		T*
F6	NC				F6	PL3B	7		C*	F6	PL3B	7		C*
F3	PL3A	3		Т	F3	PL3C	7		Т	F3	PL3C	7	LUM0_PLLT_IN_A	Т
F4	PL3B	3		C	F4	PL3D	7		C	F4	PL3D	7	LUM0_PLLC_IN_A	С
E3	PL2C	3		Т	E3	PL4A	7		T*	E3	PL4A	7		T*
E2	PL2D	3		С	E2	PL4B	7		C*	E2	PL4B	7		C*
C3	NC				C3	PL4C	7		Т	C3	PL4C	7		T
C2	NC DLOA	0		_	C2	PL4D	7		C	C2	PL4D	7		C
B1	PL2A	3		T	B1	PL5A	7		T*	B1	PL5A	7		T*
C1	PL2B	3		С	C1	PL5B	7		C*	C1	PL5B	7		C*
VCCIO3	VCCIO3	3			VCCIO7	VCCIO7	_			VCCIO7	VCCIO7	7		
GND	GNDIO3	3		_	GND	GNDIO7 PL5C	7		Т	GND	GNDIO7 PL6C	7		Т
D2	PL3C	3		T C	D2	PL5C PL5D	7		C	D2 D1	PL6C PL6D	7		C
D1	PL3D				D1		_		T*					T*
F2 G2	PL5A PL5B	3	GSRN	T C	F2 G2	PL6A PL6B	7	GSRN	C*	F2 G2	PL7A PL7B	7	GSRN	C*
E1	PL4A	3	GONN	Т	E1	PL6C	7	GSNN	Т	G2 E1	PL7C	7	GONN	Т
F1	PL4B	3		С	F1	PL6D	7		С	F1	PL7D	7		С
G4	NC	3		C	G4	PL7A	7		T*	G4	PL8A	7		T*
G5	NC				G5	PL7B	7		C*	G5	PL8B	7		C*
GND	GND	-			GND	GND	-			GND	GND	-		-
G3	PL4C	3		Т	G3	PL7C	7		Т	G3	PL8C	7		Т
H3	PL4D	3		С	H3	PL7D	7		С	H3	PL8D	7		С
H4	NC NC	-			H4	PL8A	7		T*	H4	PL9A	7		T*
H5	NC				H5	PL8B	7		C*	H5	PL9B	7		C*
-	-				VCCIO7	VCCIO7	7			VCCIO7	VCCIO7	7		
_	_				GND	GNDIO7	7			GND	GNDIO7	7		
G1	PL5C	3		Т	G1	PL8C	7		Т	G1	PL10C	7		Т
H1	PL5D	3		C	H1	PL8D	7		C	H1	PL10D	7		C
H2	PL6A	3		Т	H2	PL9A	6		T*	H2	PL11A	6		T*
J2	PL6B	3		С	J2	PL9B	6		C*	J2	PL11B	6		C*
J3	PL7C	3		Т	J3	PL9C	6		Т	J3	PL11C	6		Т
K3	PL7D	3		С	K3	PL9D	6		С	K3	PL11D	6		С
J1	PL6C	3		Т	J1	PL10A	6		T*	J1	PL12A	6		T*
-	-				VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
-	-				GND	GNDIO6	6			GND	GNDIO6	6		
K1	PL6D	3		С	K1	PL10B	6		C*	K1	PL12B	6		C*
K2	PL9A	3		Т	K2	PL10C	6		Т	K2	PL12C	6		Т
L2	PL9B	3		С	L2	PL10D	6		С	L2	PL12D	6		С
L1	PL7A	3		Т	L1	PL11A	6		T*	L1	PL13A	6		T*
M1	PL7B	3		С	M1	PL11B	6		C*	M1	PL13B	6		C*
P1	PL8D	3		С	P1	PL11D	6		С	P1	PL14D	6		С
N1	PL8C	3	TSALL	Т	N1	PL11C	6	TSALL	Т	N1	PL14C	6	TSALL	Т
L3	PL10A	3		Т	L3	PL12A	6		T*	L3	PL15A	6		T*
МЗ	PL10B	3		С	МЗ	PL12B	6		C*	МЗ	PL15B	6		C*
M2	PL9C	3		Т	M2	PL12C	6		Т	M2	PL15C	6		Т
N2	PL9D	3		С	N2	PL12D	6		С	N2	PL15D	6		С
VCCIO3	VCCIO3	3			VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
GND	GNDIO3	3			GND	GNDIO6	6			GND	GNDIO6	6		



LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280								
Ball Number	Ball Function	Bank	Dual Function	Differential				
J13	PR10C	2		Т				
M18	PR10B	2		C*				
L18	PR10A	2		T*				
GND	GNDIO2	2						
VCCIO2	VCCIO2	2						
H16	PR9D	2		С				
H14	PR9C	2		Т				
K18	PR9B	2		C*				
J18	PR9A	2		T*				
J17	PR8D	2		С				
VCC	VCC	-						
H18	PR8C	2		Т				
H17	PR8B	2		C*				
G17	PR8A	2		T*				
H13	PR7D	2		С				
H15	PR7C	2		Т				
G18	PR7B	2		C*				
F18	PR7A	2		T*				
G14	PR6D	2		С				
G16	PR6C	2		Т				
VCCIO2	VCCIO2	2						
GND	GNDIO2	2						
E18	PR6B	2		C*				
F17	PR6A	2		T*				
G13	PR5D	2		С				
G15	PR5C	2		Т				
E17	PR5B	2		C*				
E16	PR5A	2		T*				
GND	GND	-						
F15	PR4D	2		С				
E15	PR4C	2		Т				
D17	PR4B	2		C*				
D18	PR4A	2		T*				
B18	PR3D	2		С				
C18	PR3C	2		Т				
C16	PR3B	2		C*				
D16	PR3A	2		T*				
C17	PR2B	2		С				
D15	PR2A	2		Т				
VCCIO2	VCCIO2	2						
GND	GNDIO2	2						
GND	GNDIO1	1						
VCCIO1	VCCIO1	1						



LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280								
Ball Number	Ball Function	Bank	Dual Function	Differential				
A10	PT8E	0		Т				
VCCIO0	VCCIO0	0						
GND	GNDIO0	0						
A9	PT8D	0		С				
C9	PT8C	0		Т				
B9	PT8B	0		С				
F9	VCCAUX	-						
A8	PT8A	0		Т				
B8	PT7D	0		С				
C8	PT7C	0		Т				
VCC	VCC	-						
A7	PT7B	0		С				
B7	PT7A	0		Т				
A6	PT6A	0		Т				
B6	PT6B	0		С				
D8	PT6C	0		Т				
F8	PT6D	0		С				
C7	PT6E	0		T				
E8	PT6F	0		С				
D7	PT5D	0		С				
VCCIO0	VCCIO0	0						
GND	GNDIO0	0						
E7	PT5C	0		Т				
A5	PT5B	0		С				
C6	PT5A	0		Т				
B5	PT4A	0		Т				
A4	PT4B	0		С				
D6	PT4C	0		Т				
F7	PT4D	0		С				
B4	PT4E	0		Т				
GND	GND	-		<u> </u>				
C5	PT4F	0		С				
F6	PT3D	0		C				
E5	PT3C	0		T				
E6	PT3B	0		C				
D5	PT3A	0		T				
A3	PT2D	0		C				
C4	PT2C	0		T				
A2	PT2B	0						
B2	PT2A	0		T				
VCCIO0	VCCIO0	0						
GND	GNDIO0	0						
E14	GND	-						



Lead-Free Packaging

Industrial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256C-3TN100I	256	1.8V/2.5V/3.3V	78	-3	Lead-Free TQFP	100	IND
LCMXO256C-4TN100I	256	1.8V/2.5V/3.3V	78	-4	Lead-Free TQFP	100	IND
LCMXO256C-3MN100I	256	1.8V/2.5V/3.3V	78	-3	Lead-Free csBGA	100	IND
LCMXO256C-4MN100I	256	1.8V/2.5V/3.3V	78	-4	Lead-Free csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640C-3TN100I	640	1.8V/2.5V/3.3V	74	-3	Lead-Free TQFP	100	IND
LCMXO640C-4TN100I	640	1.8V/2.5V/3.3V	74	-4	Lead-Free TQFP	100	IND
LCMXO640C-3MN100I	640	1.8V/2.5V/3.3V	74	-3	Lead-Free csBGA	100	IND
LCMXO640C-4MN100I	640	1.8V/2.5V/3.3V	74	-4	Lead-Free csBGA	100	IND
LCMXO640C-3TN144I	640	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	IND
LCMXO640C-4TN144I	640	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	IND
LCMXO640C-3MN132I	640	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	IND
LCMXO640C-4MN132I	640	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	IND
LCMXO640C-3BN256I	640	1.8V/2.5V/3.3V	159	-3	Lead-Free caBGA	256	IND
LCMXO640C-4BN256I	640	1.8V/2.5V/3.3V	159	-4	Lead-Free caBGA	256	IND
LCMXO640C-3FTN256I	640	1.8V/2.5V/3.3V	159	-3	Lead-Free ftBGA	256	IND
LCMXO640C-4FTN256I	640	1.8V/2.5V/3.3V	159	-4	Lead-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200C-3TN100I	1200	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	IND
LCMXO1200C-4TN100I	1200	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	IND
LCMXO1200C-3TN144I	1200	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	IND
LCMXO1200C-4TN144I	1200	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	IND
LCMXO1200C-3MN132I	1200	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	IND
LCMXO1200C-4MN132I	1200	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	IND
LCMXO1200C-3BN256I	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	IND
LCMXO1200C-4BN256I	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	IND
LCMXO1200C-3FTN256I	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	IND
LCMXO1200C-4FTN256I	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280C-3TN100I	2280	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	IND
LCMXO2280C-4TN100I	2280	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	IND
LCMXO2280C-3TN144I	2280	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	IND
LCMXO2280C-4TN144I	2280	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	IND
LCMXO2280C-3MN132I	2280	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	IND
LCMXO2280C-4MN132I	2280	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	IND
LCMXO2280C-3BN256I	2280	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	IND
LCMXO2280C-4BN256I	2280	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	IND
LCMXO2280C-3FTN256I	2280	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	IND
LCMXO2280C-4FTN256I	2280	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	IND
LCMXO2280C-3FTN324I	2280	1.8V/2.5V/3.3V	271	-3	Lead-Free ftBGA	324	IND
LCMXO2280C-4FTN324I	2280	1.8V/2.5V/3.3V	271	-4	Lead-Free ftBGA	324	IND



MachXO Family Data Sheet Supplemental Information

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For Further Information

A variety of technical notes for the MachXO family are available on the Lattice web site.

- TN1091, MachXO sysIO Usage Guide
- TN1089, MachXO sysCLOCK Design and Usage Guide
- TN1092, Memory Usage Guide for MachXO Devices
- TN1090, Power Estimation and Management for MachXO Devices
- TN1086, MachXO JTAG Programming and Configuration User's Guide
- TN1087, Minimizing System Interruption During Configuration Using TransFR Technology
- TN1097, MachXO Density Migration
- AN8066, Boundary Scan Testability with Lattice sysIO Capability

For further information on interface standards refer to the following web sites:

- JEDEC Standards (LVTTL, LVCMOS): www.jedec.org
- PCI: www.pcisig.com



Date	Version	Section	Change Summary
April 2006 (cont.)	02.0 (cont.)	Architecture (cont.)	"Top View of the MachXO1200 Device" figure updated.
			"Top View of the MachXO640 Device" figure updated.
			"Top View of the MachXO256 Device" figure updated.
			"Slice Diagram" figure updated.
			Slice Signal Descriptions table updated.
			Routing section updated.
			sysCLOCK Phase Lockecd Loops (PLLs) section updated.
			PLL Diagram updated.
			PLL Signal Descriptions table updated.
			sysMEM Memory section has been updated.
			PIO Groups section has been updated.
			PIO section has been updated.
			MachXO PIO Block Diagram updated.
			Supported Input Standards table updated.
			MachXO Configuration and Programming diagram updated.
		DC and Switching Characteristics	Recommended Operating Conditions table - footnotes updated.
			MachXO256 and MachXO640 Hot Socketing Specifications - footnotes updated.
			Added MachXO1200 and MachXO2280 Hot Socketing Specifications table.
			DC Electrical Characteristics, footnotes have been updated.
		Supply Current (Sleep Mode) table has been updated, removed "4W" references. Footnotes have been updated.	
			Supply Current (Standby) table and associated footnotes updated.
			Intialization Supply Current table and footnotes updated.
			Programming and Erase Flash Supply Current table and associated footnotes have been updatd.
			Register-to-Register Performance table updated (rev. A 0.19).
			MachXO External Switching Characteristics updated (rev. A 0.19).
			MachXO Internal Timing Parameters updated (rev. A 0.19).
			MachXO Family Timing Adders updated (rev. A 0.19).
			sysCLOCK Timing updated (rev. A 0.19).
			MachXO "C" Sleep Mode Timing updated (A 0.19).
			JTAG Port Timing Specification updated (rev. A 0.19).
			Test Fixture Required Components table updated.
		Pinout Information	Signal Descriptions have been updated.
			Pin Information Summary has been updated. Footnote has been added.
			Power Supply and NC Connection table has been updated.
			Logic Signal Connections have been updated (PCLKTx_x> PCLKx_x)
		Ordering Information	Removed "4W" references.
			Added 256-ftBGA Ordering Part Numbers for MachXO640.
May 2006	02.1	Pinout Information	Removed [LOC][0]_PLL_RST from Signal Description table.
			PCLK footnote has been added to all appropriate pins.
August 2006	02.2	Multiple	Removed 256 fpBGA information for MachXO640.